MC100LVEL05

3.3V ECL 2-Input Differential AND/NAND

ON Semiconductor®

http://onsemi.com

Description

The MC100LVEL05 is a 2-input differential AND/NAND gate. The device is functionally equivalent to the MC100EL05 device and operates from a 3.3 V supply voltage. With propagation delays and output transition times equivalent to the EL05, the LVEL05 is ideally suited for those applications which require the ultimate in AC performance at low voltage power supplies.

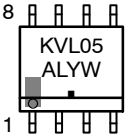
Because a negative 2-input NAND is equivalent to a 2-input OR function, the differential inputs and outputs of the device allows the LVEL05 to also be used as a 2-input differential OR/NOR gate.

Features

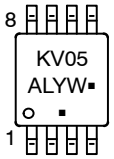
- 340 ps Propagation Delay
- High Bandwidth Output Transitions
- ESD Protection: >4 kV Human Body Model, >200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: V_{CC} = 3.0 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −3.0 V to −3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with All Inputs Open or at V_{EE}
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level 1
  For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V−0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 69 devices
- Pb−Free Packages are Available

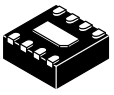
MARKING DIAGRAMS*

SOIC−8
D SUFFIX
CASE 751

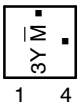


TSSOP−8
DT SUFFIX
CASE 948R





DFN8
MN SUFFIX
CASE 506AA



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
$\overline{M}$ = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)
*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

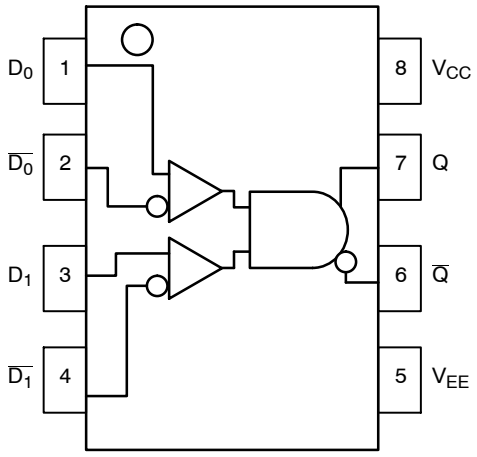


Figure 1. Logic Diagram and Pinout Assignment

Table 1. PIN DESCRIPTION

PIN	FUNCTION
D0, $\overline{D0}$; D1, $\overline{D1}$	ECL Data Inputs
Q, $\overline{Q}$	ECL Data Outputs
V_{CC}	Positive Supply
V_{EE}	Negative Supply
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−8 to 0	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	6 to 0 −6 to 0	V V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	8 SOIC	41 to 44 ± 5%	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	8 TSSOP	41 to 44 ± 5%	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T_{sol}	Wave Solder Pb Pb−Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
θ_{JC}	Thermal Resistance (Junction−to−Case)	(Note 1)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. JEDEC standard multilayer board − 2S2P (2 signal, 2 power)

Table 3. LVPECL DC CHARACTERISTICS V_{CC} = 3.3 V; V_{EE} = 0.0 V (Note 1)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		18	25		18	25		19	26	mA
V_{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V_{OL}	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	2135		2420	2135		2420	2135		2420	mV
V_{IL}	Input LOW Voltage (Single−Ended)	1490		1825	1490		1825	1490		1825	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 6)										
	Vpp < 500 mV	1.2		2.9	1.1		2.9	1.1		2.9	V
	Vpp ≧ 500 mV	1.5		2.9	1.4		2.9	1.4		2.9	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
2. Outputs are terminated through a 50 ohm resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1V.

Table 4. LVNECL DC CHARACTERISTICS V_{CC} = 0.0 V; V_{EE} = −3.3 V (Note 4)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		18	25		18	25		19	26	mA
V_{OH}	Output HIGH Voltage (Note 5)	−1085	−1005	−880	−1025	−955	−880	−1025	−955	−880	mV
V_{OL}	Output LOW Voltage (Note 5)	−1830	−1695	−1555	−1810	−1705	−1620	−1810	−1705	−1620	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	−1165		−880	−1165		−880	−1165		−880	mV
V_{IL}	Input LOW Voltage (Single−Ended)	−1810		−1475	−1810		−1475	−1810		−1475	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 6)										
	Vpp < 500 mV	−2.1		−0.4	−2.2		−0.4	−2.2		−0.4	V
	Vpp ≧ 500 mV	−1.8		−0.4	−1.9		−0.4	−1.9		−0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
5. Outputs are terminated through a 50 ohm resistor to V_{CC} − 2.0 V.
6. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1V.

Table 5. AC CHARACTERISTICS V_{CC} = 3.3 V; V_{EE} = 0.0 V or V_{CC} = 0.0 V; V_{EE} = −3.3 V (Note 7)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
t_{PLH} t_{PHL}	Propagation Delay to Output	240	260	440	240	340	440	250		450	ps
t_{JITTER}	Cycle−to−Cycle Jitter		TBD			TBD			TBD		ps
V_{PP}	Input Swing (Note 8)	150		1000	150		1000	150		1000	mV
t_r t_f	Output Rise/Fall Times Q (20% − 80%)	100		320	100	210	320	100		320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

7. V_{EE} can vary ±0.3 V.
8. V_{PP}(min) is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of ≈40.

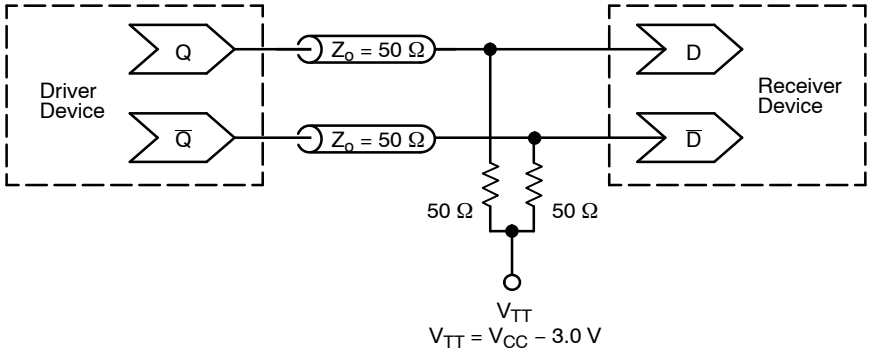


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D − Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping†
MC100LVEL05D	SOIC−8	98 Units / Rail
MC100LVEL05DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC100LVEL05DR2	SOIC−8	2500 / Tape & Reel
MC100LVEL05DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC100LVEL05DT	TSSOP−8	100 Units / Rail
MC100LVEL05DTG	TSSOP−8 (Pb−Free)	100 Units / Rail
MC100LVEL05DTR2	TSSOP−8	2500 / Tape & Reel
MC100LVEL05DTR2G	TSSOP−8 (Pb−Free)	2500 / Tape & Reel
MC100LVEL05MNR4	DFN8	1000 / Tape & Reel
MC100LVEL05MNR4G	DFN8 (Pb−Free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

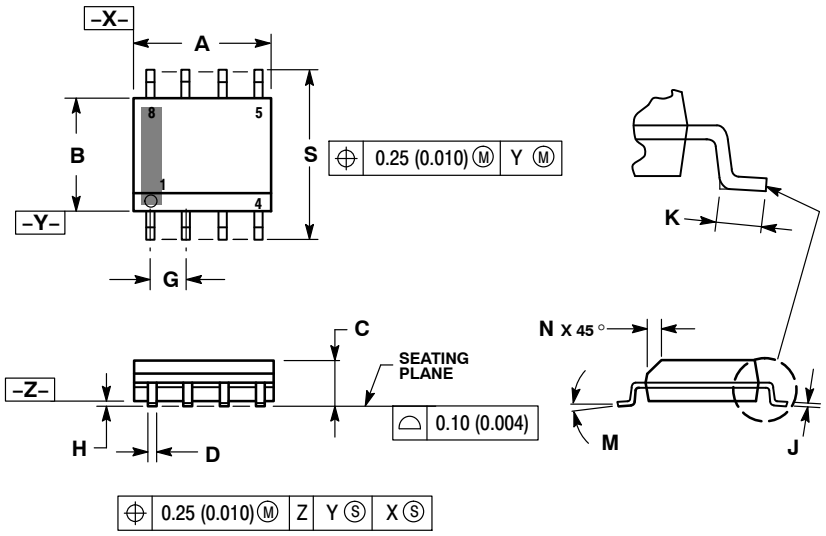
AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

AND8090/D – AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

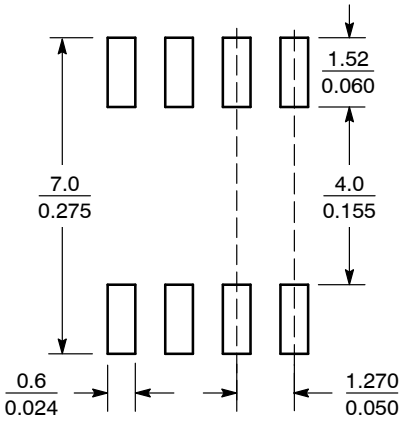
SOIC−8 NB
CASE 751−07
ISSUE AH



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

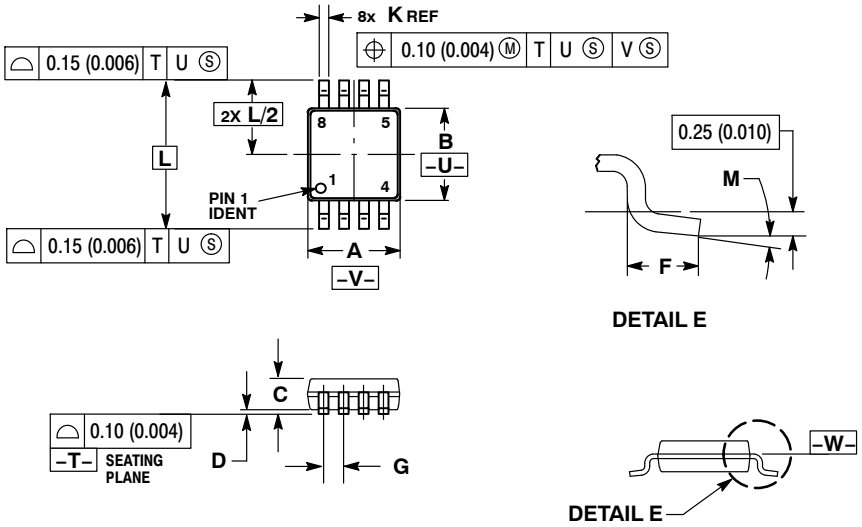


SCALE 6:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP−8
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948R−02
ISSUE A

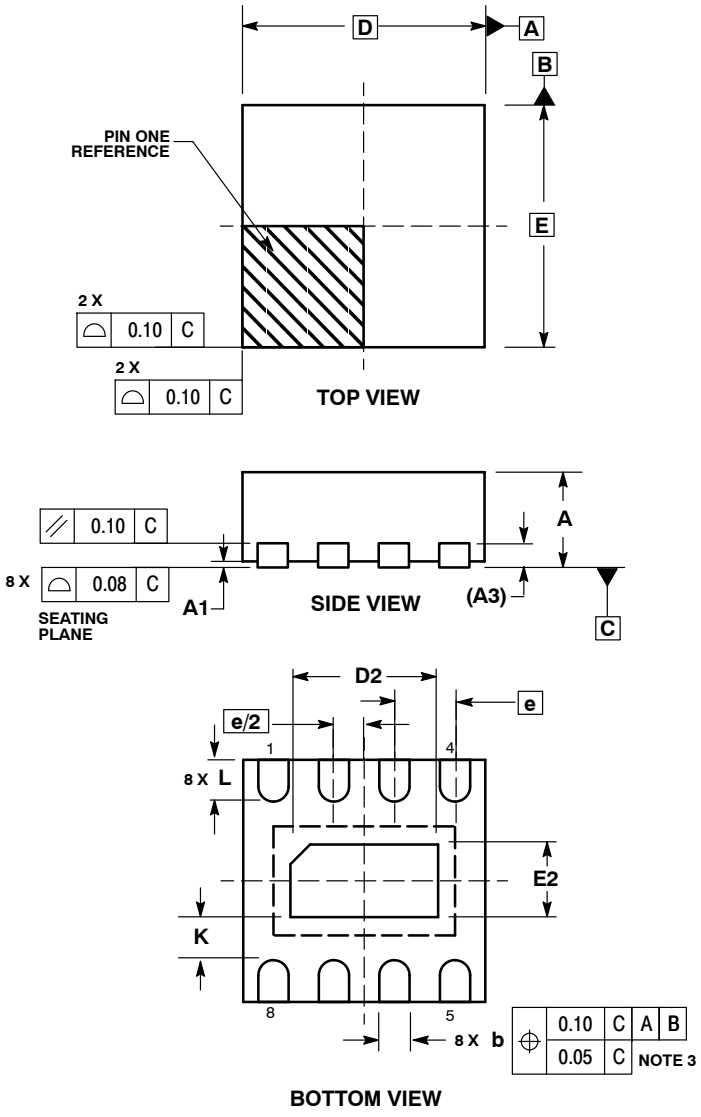


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

PACKAGE DIMENSIONS

DFN8
CASE 506AA−01
ISSUE D



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.10	1.30
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
K	0.20	−−−
L	0.25	0.35

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PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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